iJRASET

International Journal For Research in
Applied Science and Engineering Technology

INTERNATIONAL JOURNAL FOR RESEARCH

IN APPLIED SCIENCE & ENGINEERING TECHNOLOGY

Volume: 7 Issue: IV Month of publication: April 2019

DOI: <https://doi.org/10.22214/ijraset.2019.4376>

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A High-Performance Modified AXI Master Slave on-Chip Bus Design and Verification

Nandi Vardhan¹, Nithish Gangula², Jagniwas kumar³, Jayasurya Uppala⁴, B. Eshwar⁵

^{1,2,3,4}Students, ⁵Asst. Professor, Department of Electronics and Communication Engineering, Lords Institute of Engineering and Technology, Hyderabad, Telangana, India.

Abstract: Complex VLSI IC design has been revolutionized by the widespread adoption of the SoC paradigm. The benefits of the SoC approaches are numerous, including improvements in system performance, cost, size, power dissipation, and design turnaround time. As the level of chip integration continuous to advances at a fast pace, the desire for efficient interconnects rapidly increase. Currently on-chip interconnections networks are mostly implemented using traditional interconnects like buses. So, in general the performance of the SoC design heavily depends upon the efficiency of its bus structure.

This project proposes a high-performance system-on-chip bus protocol termed the AXI master-slave bus. This MSBUS is composed of a control bus (MBUS) and a data bus (SBUS). Considering the inevitable tradeoff among area, throughput and energy efficiency, the control bus is developed as a low-cost and low-power bus, and the data bus is created as a high-throughput full-duplex bus with the future of block data transfer. This bus protocol uses shared bus layers (channels), which reduce the number of wires required. That increases wire usage efficiency and simplifies the hardware interconnections as well as minimal power consumption and reduced interface complexity.

Keywords: System on-chip (SoC), wire efficiency, Xilinx, FPGA, Channel Reduction.

I. INTRODUCTION

Today, low energy on-chip bus and the reduced interface complexity are receiving lots of attention. In industry, the bus protocols like advanced microcontroller bus architecture, advanced high-performance bus (AHB) and advanced extensible Interface (AXI) from ARM Holdings, Wishbone from Silicore Corporation, open core protocol (OCP) from OCP international partnership, Core Connect from IBM, and STBus from STMicroelectronics are most commonly used. All of these buses transfer data linearly, however, in some specific applications such as computer vision, image processing, and wireless communication, data processing is usually based on the relationship of connectivity, adjacency, data neighbors, regions, and boundaries, and block data load and store. In these cases, we prefer data transfers by matrix or block rather than by linear burst. Moreover, when most of the communications occur in the same bus level or the same bus layer for some advanced bus structures such as multibus and multilayer architectures, the bandwidth can be improved. However, a large number of wires and internal logic such as multiplexers for different layer data conversions, and buffers or first-in-first-outs (FIFOs) for data flow control are necessary, which are more costly in terms of both area and energy consumptions. To overcome the aforesaid limitation, a low-cost and low-energy bus named modified AXI master-slave bus (MSBUS) is proposed. It implements the features required for low power and high throughput and balances performance with cost. To overcome the aforesaid limitation, a low-cost and low-energy bus named master-slave bus (MSBUS) is proposed in this project. It balances performance with cost and implements the features required for low power and high throughput. In addition, the bus performance features including valid data bandwidth (VDB) and dynamic energy efficiency (DEE) proposed in this project, along with the conventional metrics of transfer time consumption (TC), wire efficiency (WE), dynamic power (DP), and energy consumption (DE) are performed as analytical models in this project. They are used to analyze the bus performance and compare to the experimental results after the hardware implementation. MSBUS is composed of a control bus (MBUS) and a data bus (SBUS). MBUS stands for master bus with a single master — the Microprocessor and SBUS stands for slave bus with a single slave — the memory controller. In this bus protocol, a single bus layer is created as a shared bus with write address, read address, and write data information at master interface and another bus layer which acts as shared bus layer for READY and VALID Signals. So the number of wires (channels) used in this bus are reduced. These reduced number of bus wires (channels) increases wire usage efficiency and simplify the hardware interconnections. Moreover MBUS does not require arbitration due to the single-master structure. As an example of MSBUS based SoC shown in Fig. 1.1, several encapsulated, ready-to-use and configurable verification agents are integrated into the test bench. All the six peripherals including NON Flash, UART, I2C, SPI, GPIO, and timer controllers are MBUSs slaves. They are configured by the microprocessor through MBUS directly. On the other side, all the four application-

specific models including Wi-Fi Mac, Bluetooth 4.0 controller, USB 2.0 host controller and Security module are the slaves of MBUS and the masters of SBUS. They are controlled by the microprocessor through MBUS and access the only slave memory through SBUS.

II. LITERATURE SURVEY

The paper titled “An AMBA AHB-based reconfigurable SoC architecture using multiplicity of dedicated flyby DMA blocks” proposed a System-on-Chip (SoC) architecture for reconfigurable applications based on the AMBA High-Speed Bus (AHB). The architecture features multiple low-area fly by DMA blocks for transferring configuration data. Furthermore, the architecture eliminates the use of energy consuming instructions used in comparable commercial reconfigurable SoCs. The flyby DMA blocks achieve a reduction of up to 98% in the number of gates found in general-purpose DMA controllers. The DMA blocks also achieve the flyby throughput which halves the number of clock cycles used in conventional DMA for data transfer.

Flyby DMAC and dedicated channels DMAC adopt non- buffer data transmission mode, and the advantage of this mode is improvement of the efficiency of data transfer, but when rapid data blocks transfer proceed in equipments which are on the same group of bus or data movement in the same port that is common in audio and video codec application, this mode is no longer applicable. Because non-buffer DMAC cannot achieve write operation after reading in single-cycle.

The paper titled “Design and Implementation of an Advanced DMA Controller on AMBA-Based SoC” proposed a design and implementation of an AMBA based advanced DMA controller architecture which lies in between AHB bus and APB bus, with APB Bridge function, that is, DMAC controls directly data, address and control signals on APB bus. So it could achieve AHB operation and APB operation run in parallel. And data transfer mode can be buffer and non-buffer mode according to practical application by setting control register. AHB Master module asserts bus request signal to get access to the AHB according to parameter set, and completes data transfer between AHB and FIFO. APB Master module asserts bus request signal to gain the control of APB after arbitration with APB Bridge, and completes data transfer between APB and FIFO. However, the additional area of the separated address channels is the penalty and wire usage efficiency of these buses is less.

III. PROPOSED SYSTEM

The paper titled “A High-Performance Modified AXI Master Slave On-Chip Bus Design and Verification” Proposed a high-performance system-on-chip bus protocol. MSBUS is composed of a control bus (MBUS) and a data bus (SBUS). Considering the inevitable tradeoff among area, throughput and energy efficiency, the control bus is developed as a low-cost and low-power bus, and the data bus is created as a high-throughput full-duplex bus with the feature of block data transfer. This bus protocol uses shared bus layers, which reduces the number of wires (channels) required. That increases wire usage efficiency and simplifies the hardware interconnections.

Thus the above proposed design overcomes with the following advantages over former two designs:

- A. High wire usage efficiency,
- B. Less hardware interconnections,
- C. Minimal power consumption,
- D. Reduced interface complexity,
- E. Low cost,
- F. Block data transfer.

IV. BLOCK DAIGRAM

MSBUS is composed of a control bus (MBUS) and a data bus (SBUS). MBUS stands for master bus with a single master—the microprocessor and SBUS stands for slave bus with a single slave—the memory controller.

Fig. MSBUS block diagram

Let the prefixes “M_” and “S_” are from the master and the slave signals, respectively. Notice that “M_ADDR_WDATA” is created as a shared bus with write address, read address, and write data information. A pair of handshake signals, “M_REQ” and “S_GNT”, ensures that there is only one master occupying the write or read channel at the same time. The other SBUS signals are categorized into five packets.

- A. Command (M_CMD_PKT[42:0])
- B. Write data (M_WD_PKT[31:0]),
- C. write data mask (M_WBM_PKT[3:0]),
- D. read data (M_RD_PKT[31:0]),
- E. Response (S_RSP_PKT[1:0]).

V. TIMING DIAGRAMS

MBUS defines the SINGLE transfer mode with at least one-cycle command and one-cycle data. It is optimized for minimal power consumption and reduced interface complexity. As shown in Fig. 5.1(a), let the prefixes “M_” and “S_” are from the master and the slave signals, respectively hereafter. Notice that “M_ADDR_WDATA” is created as a shared bus with write address, read address, and write data information. It increases wire usage efficiency and simplifies the hardware interconnection. Second, MBUS does not require arbitration due to the single-master structure, so the command stage takes only one master cycle. Third, the valid signal (S_VLD) used to acknowledge the request is necessary to synchronize signals crossing between master and slave clock domain and avoid command FIFO overflows. Finally, a response delay timer is defined in the MBUS protocol to detect command errors. If the current response is a timeout, the command is indicated as “error” and must be “retried” or “discarded” by the master.

Fig. MSBUS timing diagrams.

(a) MBUS protocol. (b) SBUS protocol.

Fig. 5.1(b) shows an example of the timing diagram of SBUS. A pair of handshake signals, “M_REQ” and “S_GNT,” ensures that there is only one master occupying the write or read channel at the same time. The other SBUS signals are categorized into five packets: command, write data, write data mask, read data, and response. The command packet includes transfer direction, size, and initial address information. The write data mask packet indicates the valid byte of the current word unit write data, and the response packet indicates that the current write data is ready or the read data is valid. Notice that SBUS provides the command preprocessing scheme to avoid time consumption of multiple command stages.

VI. FLOWCHART

VII. SIMULATION RESULTS

A. Write Transaction

Fig. Write transaction

B. Read Transactions

Fig. Read transaction

VIII. CONCLUSION

This paper proposed a high-performance bus with shared bus layers (channels), reduced interface complexity, minimal power consumption, and high throughput. This bus protocol uses shared bus layers, which reduces the number of bus layers required. These reduced number of bus layers, increases wire usage efficiency and simplifies the hardware interconnections as well as minimal power consumption and reduced interface complexity.

In this paper, VERILOG HDL programming has been used in the implementation of MSBUS.

And the Programming tool used for the implementation is Xilinx ISE-13.1. The design is implemented using FPGA Spartan 3-E.

The single-processor and multiclient bus structure of MSBUS reduces resource utilization and energy consumption and limits the complexity of circuits. Therefore, the MSBUS protocol is very desirable for small-scale embedded systems with requirements of a low-cost interface and high-energy efficiency.

IX. FUTURE SCOPE

The MSBUS design proposed in this paper focused on providing the bus with shared bus layers (channels) which reduced interface complexity, minimal power consumption, and high throughput. However, the MSBUS protocol is designed with a single processor (master) and multiple slaves. A direction for future work involves the creation of multi master with the above features. So that its applications are extended to large-scale embedded systems.

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AUTHOUR'S OUTLINE

- 1) **Mr. Nandi Vardhan** is currently pursuing his B.Tech in Electronics and Communication Engineering from Lords Institute of Engineering and Technology, Himayathsagar, Hyderabad, TS, India.
E-mail: Nandivardhan999@gmail.com
- 2) **Mr. Nithish Gangula** is currently pursuing his B.Tech in Electronics and Communication Engineering from Lords Institute of Engineering and Technology, Himayathsagar, Hyderabad, TS, India.
E-mail: Gangulanithish01@gmail.com
- 3) **Mr. Jagniwas Kumar** is currently pursuing his B.Tech in Electronics and Communication Engineering from Lords Institute of Engineering and Technology, Himayathsagar, Hyderabad, TS, India.
E-mail: Jagniwaskumar01@gmail.com
- 4) **Mr. Jayasurya Uppala** is currently pursuing his B.Tech in Electronics and Communication Engineering from Lords Institute of Engineering and Technology, Himayathsagar, Hyderabad, TS, India.
E-mail: Uppalajayasurya.1998@gmail.com
- 5) **Mr. B. Eshwar**, completed BE and ME from OU. Has three year experience in teaching. Field of interest is VLSI, Analog electronics, Pulse and Digital circuits. Presently working as Asst. Professor in Department of Electronics and Communication Engineering, Lords Institute of Engineering and Technology, Himayathsagar, Hyderabad, TS, India.
E-mail: Beshwar@lords.ac.in

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